

1-534998-4 ✓ ACTIVE

AMPMODU | Modu Connector System

TE Internal #: 1-534998-4

PCB Mount Receptacle, Vertical, Board-to-Board, 28 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System

[View on TE.com >](#)



Connectors > PCB Connectors > PCB Headers & Receptacles



EU RoHS Compliance: **Not Compliant**

EU ELV Compliance: **Compliant with Exemptions**

PCB Connector Assembly Type: **PCB Mount Receptacle**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Features

Other

EU RoHS Compliance	Not Compliant
EU ELV Compliance	Compliant with Exemptions

Product Type Features

Applied Pressure	Standard
PCB Connector Assembly Type	PCB Mount Receptacle
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Board-to-Board Configuration	Parallel
Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	28
Number of Rows	2

Electrical Characteristics

Operating Voltage	333 VAC
Insulation Resistance	5000 MΩ
Dielectric Withstanding Voltage (Max)	750 VAC



Body Features

Connector Profile	Low
Primary Product Color	Black

Contact Features

Contact Mating Area Plating Material Thickness	.762 μ m[30 μ in]
Mating Square Post Dimension	.64 mm[.025 in]
PCB Contact Termination Area Plating Material Thickness	3.81 – 7.61 μ m
Contact Shape & Form	Round
Contact Protection Type	Closed Entry Housing
Contact Mating Area Length	3.77 mm[.148 in]
Contact Base Material	Phosphor Bronze
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Mating Area Plating Material	Gold
Contact Type	Socket
Contact Current Rating (Max)	2 A

Termination Features

Rectangular Termination Post & Tail Width	.7 mm[.028 in]
Rectangular Termination Post & Tail Thickness	.2 mm[.008 in]
Termination Post & Tail Length	3.18 mm[.125 in]
Termination Method to PCB	Through Hole - Solder

Mechanical Attachment

PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Mating Alignment	Without

Housing Features

Mating Entry Location	Top
Housing Material	Thermoplastic
Centerline (Pitch)	2.54 mm[.1 in]

Dimensions

Row-to-Row Spacing	2.54 mm[.1 in]
Stack Height	9.02 mm[.355 in]



PCB Thickness (Recommended)	1.57 mm[.055 – .094 in]
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Connector Height	5.03 mm[.198 in]
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Usage Conditions

Housing Temperature Rating	Standard
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Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]
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Operation/Application

Solder Process Feature	Board Standoff
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Circuit Application	Signal
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Industry Standards

Compatible With Approved Standards Products	UL E28476, CSA LR7189
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UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Quantity	16
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Packaging Method	Tube, Box
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Not Compliant
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EU ELV Directive 2000/53/EC	Compliant with Exemptions
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China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) SVHC > Threshold: Pb (13% in Component Part)
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Article Safe Usage Statements:

Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.

Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
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Solder Process Capability	Wave solder capable to 240°C
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Product Compliance Disclaimer

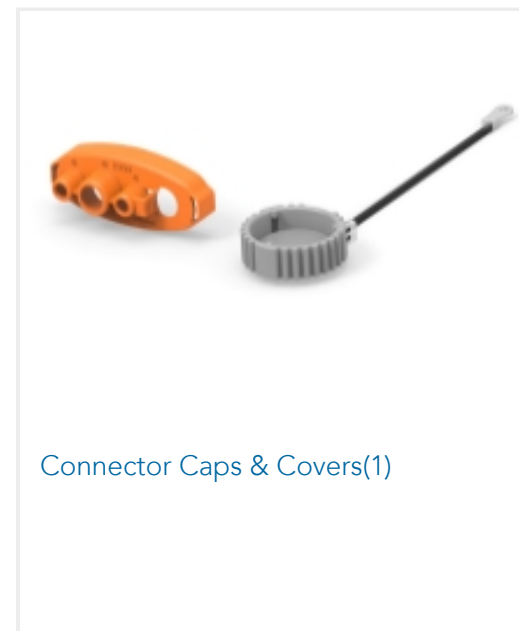
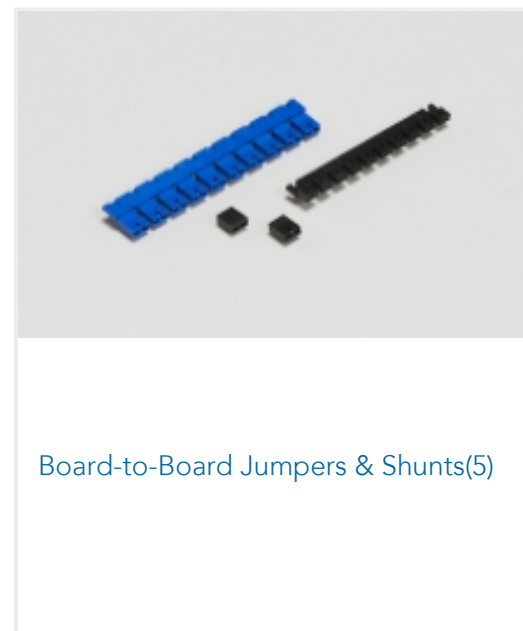
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products

will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Also in the Series | Modu Connector System



Customers Also Bought





Documents

Product Drawings

[28 MODIV VRT DR CE 100/125](#)

English

CAD Files

Customer View Model

[ENG_CVM_CVM_1-534998-4_R.2d_dxf.zip](#)

English

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_1-534998-4_R.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1-534998-4_R.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

[Application Specification](#)

English